

LOCTITE ABLESTIK GA2W

August 2012

PRODUCT DESCRIPTION

LOCTITE ABLESTIK GA2W provides the following product characteristics:

Technology	Acrylic	
Appearance	Off-white	
Cure	Heat cure	
Product Benefits	Non-conductive	
	 Ultra-low modulus 	
	Low stress	
	 Low chip warpage 	
	 Improved viscosity 	
	 Thixotropic 	
	 Good dispensability 	
рН	3.9	
Application	Die attach	
Filler Type	Silica	
Typical Assembly	CCD/CMOS and	Optoelectronic
Applications	assembly	

LOCTITE ABLESTIK GA2W single component adhesive is designed for CCD/CMOS die attach bonding applications. This adhesive can be cured using directed heat energy or hot plate curing techniques.

TYPICAL PROPERTIES OF UNCURED MATERIAL

Thixotropic Index (0.5/5 rpm)	5.4
Viscosity, Brookfield CP51, 25 °C, mPa·s (cP):	
Speed 5 rpm	10,000
Work Life @ 25°C, hours	48
Shelf Life @ -40°C, days	365
Flash Point - See SDS	

TYPICAL CURING PERFORMANCE Weight Loss on Cure

Weight Loss on Cure, %

Cure Schedule

30 minute ramp to 175°C + 15 minutes @ 175°C

Alternative Cure Schedule

1 minute @ 150°C on hot plate

The above cure profiles are guideline recommendations. Cure conditions (time and temperature) may vary based on customers' experience and their application requirements, as well as customer curing equipment, oven loading and actual oven temperatures.

TYPICAL PROPERTIES OF CURED MATERIAL

Physical Properties :

i iljoiou i roportioo :	
Coefficient of Thermal Expansion :	
Below Tg, ppm/°C	58
Above Tg, ppm/°C	164
Glass Transition Temperature, Tan Δ Max, °C	25
Tensile Modulus, DMTA :	
@ 25 °C	N/mm² 70 (psi) (10,590)
@ 50 °C	N/mm ² 20 (psi) (2,800)
@ 100 °C	N/mm ² 10 (psi) (1,280)
@ 150 °C	N/mm ² 8 (psi) (1,160)
@ 200 °C	N/mm ² 9
	(psi) (1,300)
Extractable Ionic Content, @ 100°C ppm:	
Chloride (Cl-)	<5
Sodium (Na+)	<1
Potassium (K+)	N/D
Water Extract Conductivity, µmhos	47.3
Moisture Absorption @ Saturation, wt.% @ 8	5°C/85°RH 0.1

TYPICAL PERFORMANCE OF CURED MATERIAL

Die Shear Strength :

$5 \times 5 \text{ mm Si die, kg-f/mm}^2$,			
Substrate	@150°C	@175°C	
BT & AUS-5 Solde Mas	-	0.78	

Chip Warpage, µm:

0.4

15 X 15 mm Si die

@ 25°C after cure, 25µm BLT

Substrate	@ 120°C in hot plate	@ 150ºC in oven
0.52, BT & AUS-5 Solder Mask		24

GENERAL INFORMATION

For safe handling information on this product, consult the Safety Data Sheet, (SDS).



THAWING:

- 1. Allow container to reach room temperature before use.
- 2. After removing from the freezer, set the syringes to stand vertically while thawing.
- 3. DO NOT open the container before contents reach 25°C temperature. Any moisture that collects on the thawed container should be removed prior to opening the container.
- 4. DO NOT re-freeze. Once thawed to 25°C, the adhesive should not be re-frozen.

DIRECTIONS FOR USE

- 1. This adhesive is designed for pin transfer, dot dispensing and/or syringe applications.
- 2. Dispense the desired amount of material and place slider/die/crystal into deposit using downward force to achieve desired bondline.

Not for product specifications

The technical data contained herein are intended as reference only. Please contact your local quality department for assistance and recommendations on specifications for this product.

STORAGE:

Store product in the unopened container in a dry location. Storage information may be indicated on the product container labeling.

Optimal Storage: -40 °C. Storage below minus (-)40 °C or greater than minus (-)40 °C can adversely affect product properties.

Material removed from containers may be contaminated during use. Do not return product to the original container. Henkel Corporation cannot assume responsibility for product which has been contaminated or stored under conditions other than those previously indicated. If additional information is required, please contact your local Technical Service Center or Customer Service Representative.

Conversions

 $(^{\circ}C \ge 1.8) + 32 = ^{\circ}F$ kV/mm x 25.4 = V/mil mm / 25.4 = inches N x 0.225 = lb N/mm x 5.71 = lb/in psi x 145 = N/mm² MPa = N/mm² N·m x 8.851 = lb·in N·m x 0.738 = lb·ft N·mm x 0.142 = oz·in mPa·s = cP

Disclaimer Note:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. The product can have a variety of different applications as well as differing application and working conditions in your environment that are beyond our control. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended

applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Belgium NV, Henkel Electronic Materials NV, Henkel Nederland BV, Henkel Technologies France SAS and Henkel France SA please additionally note the following:

In case Henkel would be nevertheless held liable, on whatever legal ground, Henkel's liability will in no event exceed the amount of the concerned delivery.

In case products are delivered by Henkel Colombiana, S.A.S. the following disclaimer is applicable:

The information provided in this Technical Data Sheet (TDS) including the recommendations for use and application of the product are based on our knowledge and experience of the product as at the date of this TDS. Henkel is, therefore, not liable for the suitability of our product for the production processes and conditions in respect of which you use them, as well as the intended applications and results. We strongly recommend that you carry out your own prior trials to confirm such suitability of our product.

Any liability in respect of the information in the Technical Data Sheet or any other written or oral recommendation(s) regarding the concerned product is excluded, except if otherwise explicitly agreed and except in relation to death or personal injury caused by our negligence and any liability under any applicable mandatory product liability law.

In case products are delivered by Henkel Corporation, Resin Technology Group, Inc., or Henkel Canada, Inc.the following disclaimer is applicable:

The data contained herein are furnished for information only and are believed to be reliable. We cannot assume responsibility for the results obtained by others over whose methods we have no control. It is the user's responsibility to determine suitability for the user's purpose of any production methods mentioned herein and to adopt such precautions as may be advisable for the protection of property and of persons against any hazards that may be involved in the handling and use thereof. In light of the foregoing, Henkel Corporation specifically disclaims all warranties expressed or implied, including warranties of merchantability or fitness for a particular purpose, arising from sale or use of Henkel Corporation's products. Henkel Corporation specifically disclaims any liability for consequential or incidental damages of any kind, including lost profits. The discussion herein of various processes or compositions is not to be interpreted as representation that they are free from domination of patents owned by others or as a license under any Henkel Corporation patients that may cover such processes or compositions. We recommend that each prospective user test his proposed application before repetitive use, using this data as a guide. This product may be covered by one or more United States or foreign patents or patent applications.

Trademark usage Except as otherwise noted, all trademarks in this document are trademarks of Henkel Corporation in the U.S. and elsewhere.
(B) denotes a trademark registered in the U.S. Patent and Trademark Office.

Reference 1